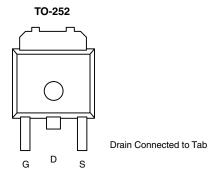


N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A)	Q _g (Typ.)			
60	0.073 at V _{GS} = 10 V	18	19.8			
00	0.085 at V _{GS} = 4.5 V	15	19.8			



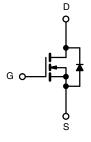
FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
 Material categorization:
 - Material categorization: For definitions of compliance please see



APPLICATIONS

- DC/DC Converters
- DC/AC Inverters
- Motor Drives



N-Channel MOSFET

ABSOLUTE MAXIMUM RAT	FINGS (T _C = 25 °C, unless o	otherwise noted)		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	v	
Gate-Source Voltage		V _{GS}	± 20	v
Continuous Drain Current	T _C = 25 °C		18	
Continuous Drain Current	T _C = 70 °C	I _D	14	А
Pulsed Drain Current (t = 300 µs)	I _{DM}	25	A	
Avalanche Current	I _{AS}	15		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	11.25	mJ
Maximum Power Dissipation ^a	T _C = 25 °C	Р	41.7 ^b	w
	T _A = 25 °C ^c	P _D	2.1	vv
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/W		
Junction-to-Case (Drain)	R _{thJC}	3	0/11		

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).

d. Base on T_C = 25 °C.

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static			•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$				v
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		3.0	v
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 150 ^{\circ}\text{C}$			250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10$ V, $V_{GS} = 10$ V	20			А
Durin Course On Chate Desistence		V _{GS} = 10 V, I _D = 6.6 A		0.073		0
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 6 \text{ A}$		0.085		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 6.6 A		25		S
Dynamic ^b	•					
Input Capacitance	C _{iss}			660		pF
Output Capacitance	C _{oss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz		85		
Reverse Transfer Capacitance	C _{rss}			40		
Total Gate Charge ^c	Qg			19.8	30	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 6.6 \text{ A}$		3.6		nC
Gate-Drain Charge ^c	Q _{gd}			4.1		
Gate Resistance	R _q	f = 1 MHz	0.4	2	4	Ω
Turn-On Delay Time ^c	t _{d(on)}			8	16	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_{I} = 9.6 \Omega$		11	20	-
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 5.2 \text{ Å}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		18	27	
Fall Time ^c	t _f			5	10	
Turn-On Delay Time ^c	t _{d(on)}			38	57	ns
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_{I} = 9.6 \Omega$		58	87	-
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 5.2 \text{ A}, V_{\text{GEN}} = 4.5 \text{ V}, R_g = 1 \Omega$		18	27	
Fall Time ^c	t _f			8	16	
Drain-Source Body Diode Ratings a	nd Characteri	stics ^b T _C = 25 °C				
Continuous Current	۱ _S				18	^
Pulsed Current	I _{SM}				25	A
Forward Voltage ^a	V _{SD}	I _F = 5.2 A, V _{GS} = 0 V		0.8	1.5	V
Reverse Recovery Time	t _{rr}			34	51	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 5.2 A, dl/dt = 100 A/μs		3	5	Α
Reverse Recovery Charge	Q _{rr}	1		50	75	nC

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

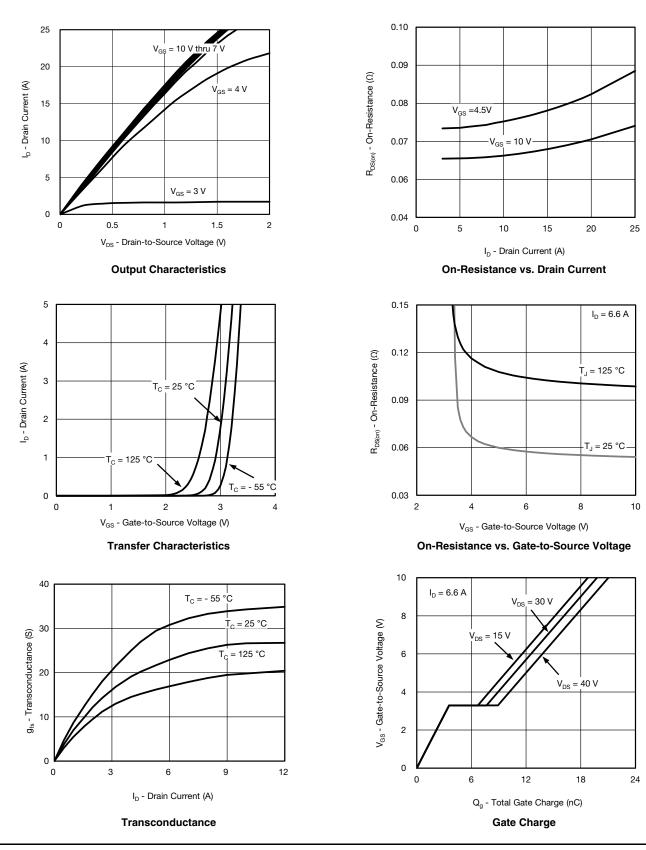
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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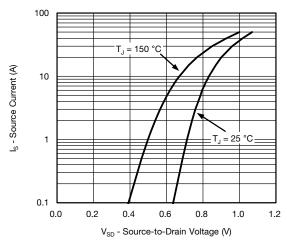




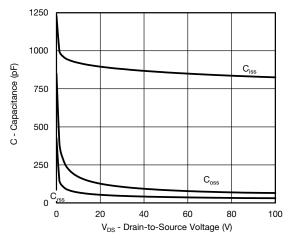




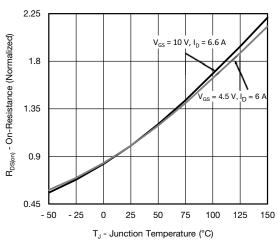
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



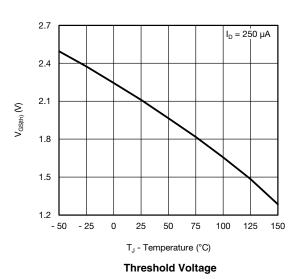
Source-Drain Diode Forward Voltage





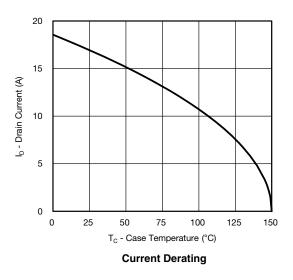


On-Resistance vs. Junction Temperature



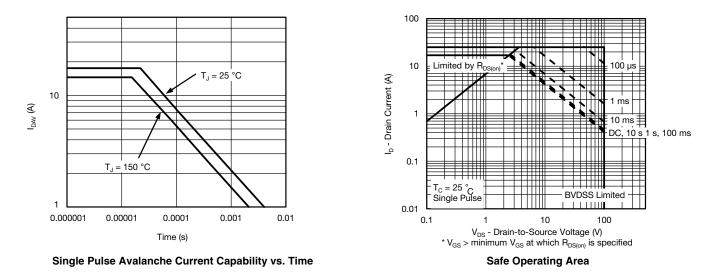
127 I_D = 250 μA V_{DS} (V) Drain-to-Source Voltage 122 117 112 107 102 - 25 0 25 50 75 100 150 - 50 125 T₁ - Temperature (°C)

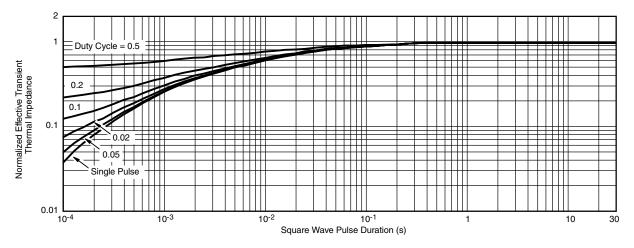
Drain Source Breakdown vs. Junction Temperature





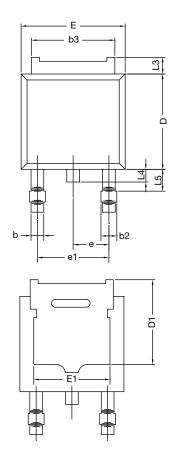
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



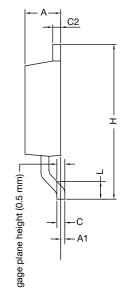


Normalized Thermal Transient Impedance, Junction-to-Case





TO-252AA Case Outline



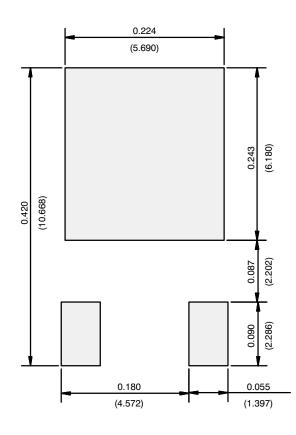
	MILLIN	IETERS	INC	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	4.10	-	0.161	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC		0.090 BSC			
e1	4.56 BSC		0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.01	1.52	0.040	0.060		
ECN: T16- DWG: 534	0236-Rev. P, ⁻ 7	16-May-16				

Notes

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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